

SIMATIC ET 200S COMPACT

**Meyer Burger AG, Switzerland –
Manufacturing and processing of materials**

Requirements

Meyer Burger AG has over 50 years of experience in cutting hard and brittle materials and special crystals such as silicon and sapphire. The global sales and service network of Meyer Burger has a separate subsidiary in China and Japan as well as service centers in Germany and the Philippines. The main industries are the photovoltaic, semiconductor and optical and ceramics industries. More than 3,500 systems have been installed worldwide.

Hard and brittle materials have to be cut faster, more accurately and with less loss of material. This places stringent demands on the control system and the I/O: Compact size, fast response, reduced wiring outlay and modular construction of machines.

Solution

To meet these requirements, Meyer Burger relies on the compact distributed I/O ET 200S COMPACT. Thanks to their high channel density, it was not necessary to expand the stations. Add-on terminals were also used to enable 3-wire connection without the need for additional terminal blocks. This saves space and time during wiring up. The existing bus system was PROFIBUS DP, so this was also used for the new solution.

Benefits

The use of ET 200S COMPACT provides several benefits: The signals of the different sensors and switches can now be bundled and evaluated by the existing PROFIBUS. Complete pre-assembly (wiring) of the modules means that on final installation only the bus cable has to be connected. Time-consuming wiring of modules in the control cabinet is therefore reduced.

"By using ET 200S COMPACT, we can acquire control variables on our machines decentralized and transfer them to the controller over PROFIBUS. Fewer signals therefore have to be routed to the control cabinet. This reduces the wiring costs and increases our flexibility considerably. We can therefore reduce throughput time at final assembly."

Dr. Urs Schönholzer, Head of Development

